

VP7000 vacuum

Vapor Phase Vacuum Soldering Systems High-Performance Inline Systems for Large Series

ASSCON vapor phase reflow soldering systems set standards in soldering technology. The VP7000 vacuum inline systems are based on advanced patented high-tech soldering methods, and offer outstanding soldering quality in large series production.

MULTI VACUUM FOR BEST RESULTS

The innovative inline soldering system for large series users is equipped with the patented Multi Vacuum technology. In the Multi Vacuum soldering process products are placed under a vacuum both before and during melting of the solder paste. Thanks to the benefits of modern ASSCON vapor phase soldering technology with vacuum handling, hitherto unrivalled levels are achieved in soldering quality. Void-free soldering is particularly important in the case of large-area, energy transmitting solder joints. The excellent soldering result is also supported by Dynamic Profiling – a process for automatically controlling the optimum soldering profile in series production.

INLINE PRODUCTION FOR HIGH VOLUME

The system is designed for carrier-free product processing integration into large series production lines. Electrically width-adjusted conveying systems and center support permit fast straight-forward adjustment for flexible production. The system is modularly designed, and consists of loading station, soldering zone, vacuum chamber and cooling zone. Aside from the low energy consumption rates ensured by the process, the system also impresses with fail-safe operation. Multi Vacuum soldering is the answer to the challenges of the future. ASSCON is the leader in the field of vapor phase soldering technology and develops innovative processes.

PRODUCT BENEFITS

- perfect solder joints thanks to the use of advanced technology
- reproducible process conditions
- no overheating or destruction of electronic components
- low energy costs thanks to smart energy management
- low overall running costs
- full traceability capability
- product changing without waiting times
- void Free Soldering due to Multi Vacuum Technology

70 %

less energy
consumption

< 1 %

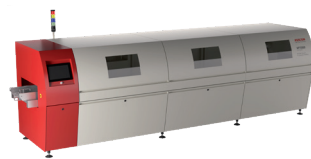
voids after
multi vacuum
treatment

VP7000 vacuum

Vapor Phase Soldering Systems for Large Series

RANGE OF APPLICATION

INLINE OPERATION | SERIES PRODUCTION | LARGE SERIES



PRODUCT

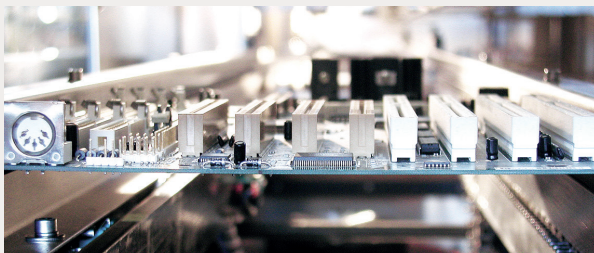
VP7000-200

TECHNICAL DATA

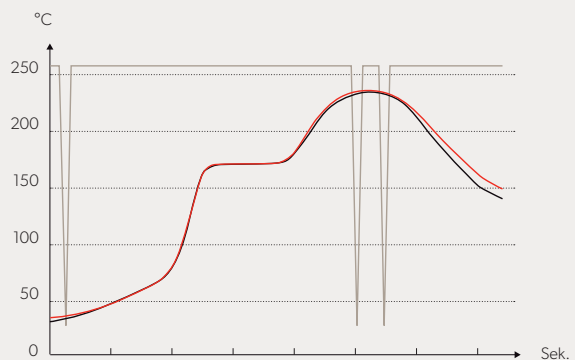
Transport	single lane
Max. solder product format	up to 520 x 450 mm
Longboard	1040 x 450 mm
Component height	up to 55 mm
Ready for use	ca. 45 min.
Vacuum pump	0.5 mbar
Connection power	20 kW

MULTI VACUUM

Due to a vacuum step following the soldering process, inclusions (voids) are removed from the solder joint before the solidification phase has taken place.



The systems are equipped with electrically width-adjusted conveying systems and center support.



Multi Vacuum Technology enables up to three vacuum steps per soldering cycle.

asscon.de

ASSCON Systemtechnik-Elektronik GmbH
Messerschmittring 35 • 86343 Königsbrunn • Germany
P +49 8231 . 95991 . 0 • F +49 8231 . 95991 . 90